

20A, 600V N-CHANNEL MOSFET

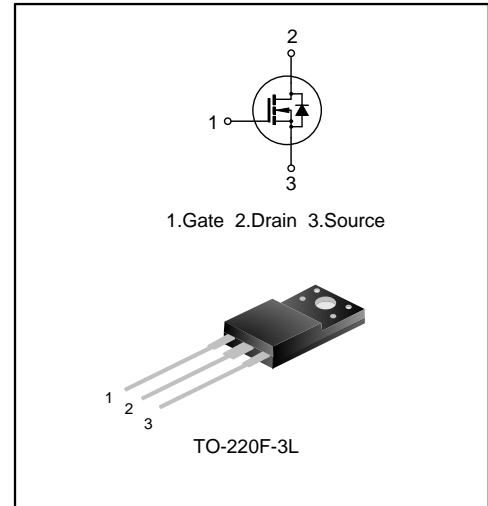
GENERAL DESCRIPTION

SVF20N60F is an N-channel enhancement mode power MOS field effect transistor which is produced using Silan proprietary F-Cell™ structure VDMOS technology. The improved planar stripe cell and the improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are widely used in AC-DC power suppliers, DC-DC converters and H-bridge PWM motor drivers.

FEATURES

- ◆ 20A,600V, $R_{DS(on)(typ.)}=0.28\Omega@V_{GS}=10V$
- ◆ Low gate charge
- ◆ Low Crss
- ◆ Fast switching
- ◆ Improved dv/dt capability



ORDERING INFORMATION

| Part No. | Package | Marking | Hazardous Substance Control | Packing Type |
|-----------|------------|-----------|-----------------------------|--------------|
| SVF20N60F | TO-220F-3L | SVF20N60F | Pb free | Tube |

ABSOLUTE MAXIMUM RATINGS (T_A=25°C UNLESS OTHERWISE NOTED)

| Characteristics | Symbol | Ratings | Unit |
|---|------------------|-----------------------|------|
| Drain-Source Voltage | V _{DS} | 600 | V |
| Gate-Source Voltage | V _{GS} | ±30 | V |
| Drain Current | I _D | T _C =25°C | 20 |
| | | T _C =100°C | 12.6 |
| Drain Current Pulsed | I _{DM} | 80 | A |
| Power Dissipation(T _C =25°C) -Derate above 25°C | P _D | 74 | W |
| | | 0.59 | W/°C |
| Single Pulsed Avalanche Energy (Note 1) | E _{AS} | 1433 | mJ |
| Operation Junction Temperature Range | T _J | -55~+150 | °C |
| Storage Temperature Range | T _{stg} | -55~+150 | °C |

THERMAL CHARACTERISTICS

| Characteristics | Symbol | Ratings | Unit |
|---|------------------|---------|------|
| Thermal Resistance, Junction-to-Case | R _{θJC} | 1.69 | °C/W |
| Thermal Resistance, Junction-to-Ambient | R _{θJA} | 62.5 | °C/W |

ELECTRICAL CHARACTERISTICS (T_J=25°C UNLESS OTHERWISE NOTED)

| Characteristics | Symbol | Test conditions | Min. | Typ. | Max. | Unit |
|---|---------------------|---|------|------|------|------|
| Drain -Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V, I _D =250μA | 600 | -- | -- | V |
| Drain-Source Leakage Current | I _{DSS} | V _{DS} =600V, V _{GS} =0V | -- | -- | 1.0 | μA |
| Gate-Source Leakage Current | I _{GSS} | V _{GS} =±30V, V _{DS} =0V | -- | -- | ±100 | nA |
| Gate Threshold Voltage | V _{GS(th)} | V _{GS} =V _{DS} , I _D =250μA | 2.0 | -- | 4.0 | V |
| Static Drain- Source On State Resistance | R _{DS(on)} | V _{GS} =10V, I _D =10A | -- | 0.28 | 0.35 | Ω |
| Input Capacitance | C _{iss} | V _{DS} =25V, V _{GS} =0V, f=1.0MHz | -- | 2708 | -- | pF |
| Output Capacitance | C _{oss} | | -- | 293 | -- | |
| Reverse Transfer Capacitance | C _{rss} | | -- | 6.6 | -- | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =300V, I _D =20A, R _G =25Ω (Note2,3) | -- | 27 | -- | ns |
| Turn-on Rise Time | t _r | | -- | 44 | -- | |
| Turn-off Delay Time | t _{d(off)} | | -- | 82 | -- | |
| Turn-off Fall Time | t _f | | -- | 44 | -- | |
| Total Gate Charge | Q _g | V _{DS} =480V, I _D =20A, V _{GS} =10V (Note2,3) | -- | 47 | -- | nC |
| Gate-Source Charge | Q _{gs} | | -- | 14 | -- | |
| Gate-Drain Charge | Q _{gd} | | -- | 15 | -- | |

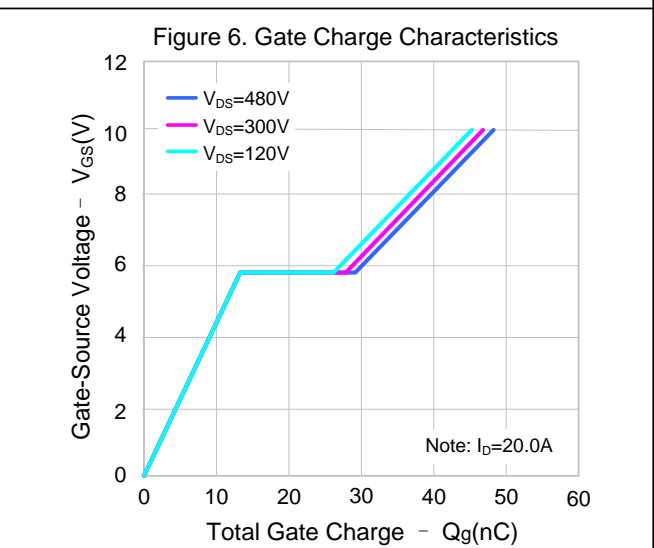
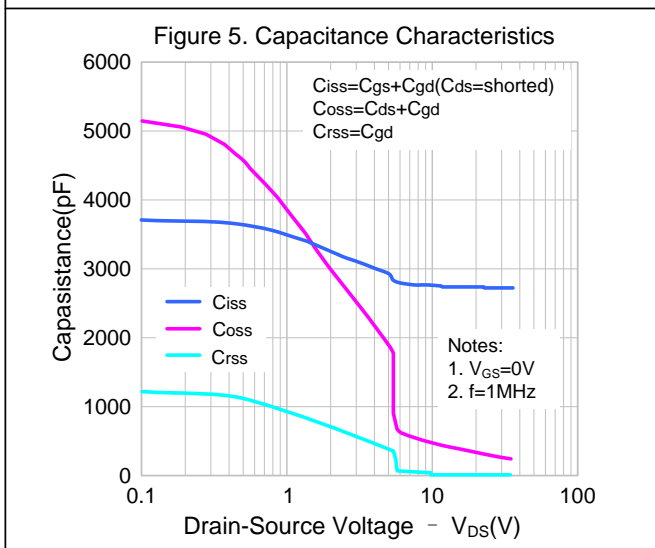
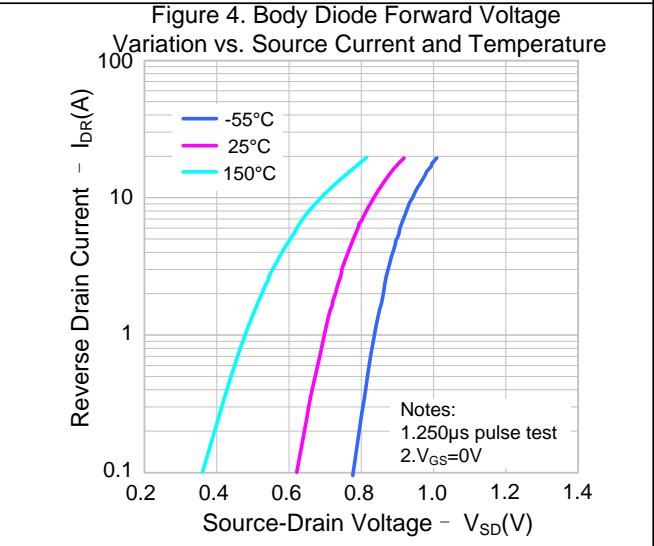
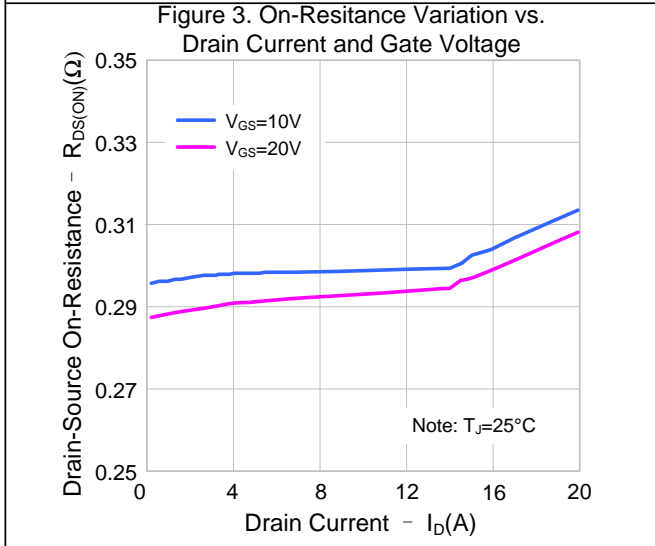
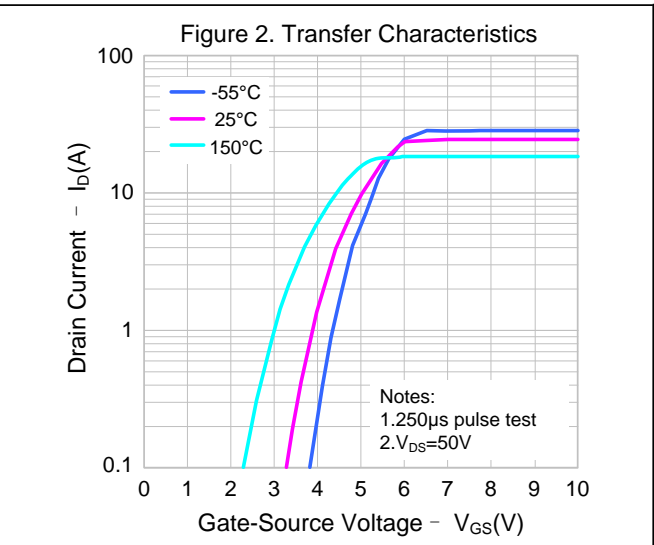
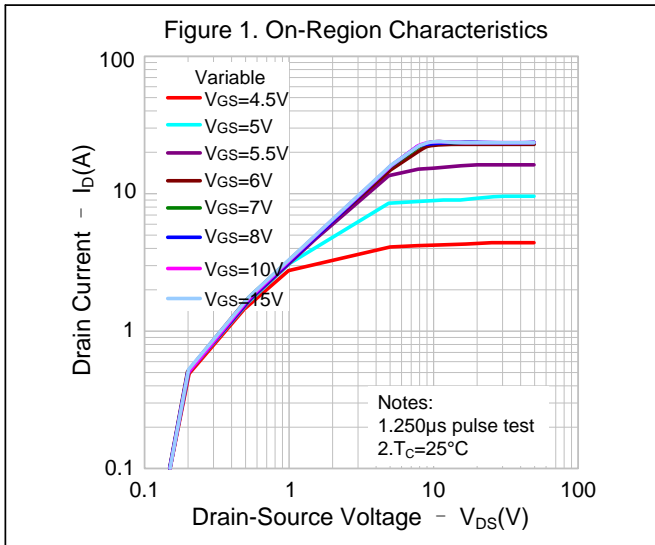
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

| Characteristics | Symbol | Test conditions | Min. | Typ. | Max. | Unit |
|---------------------------|----------|-------------------------------|------|------|------|---------|
| Continuous Source Current | I_S | Integral Reverse P-N Junction | -- | -- | 20 | A |
| Pulsed Source Current | I_{SM} | Diode in the MOSFET | -- | -- | 80 | |
| Diode Forward Voltage | V_{SD} | $I_S=20A, V_{GS}=0V$ | -- | -- | 1.4 | V |
| Reverse Recovery Time | T_{rr} | $I_S=20A, V_{GS}=0V,$ | -- | 630 | -- | ns |
| Reverse Recovery Charge | Q_{rr} | $di_F/dt=100A/\mu s$ (Note 2) | -- | 8.2 | -- | μC |

Notes:

1. $L=30mH, I_{AS}=9.45A, V_{DD}=100V, R_G=25\Omega$, starting $T_{BJB}=25^\circ C$;
2. Pulse Test: Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;
3. Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

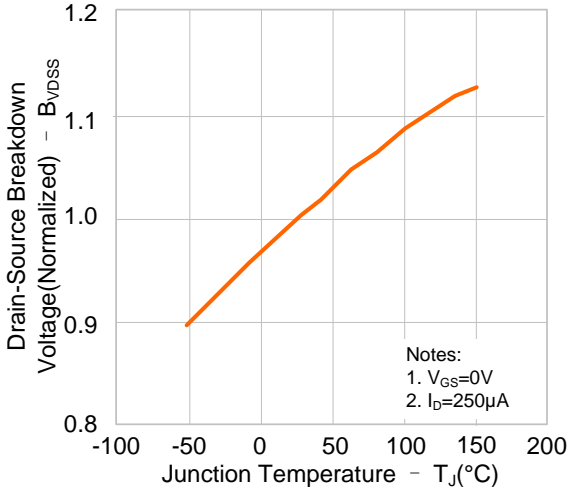


Figure 8. On-resistance Variation vs. Temperature

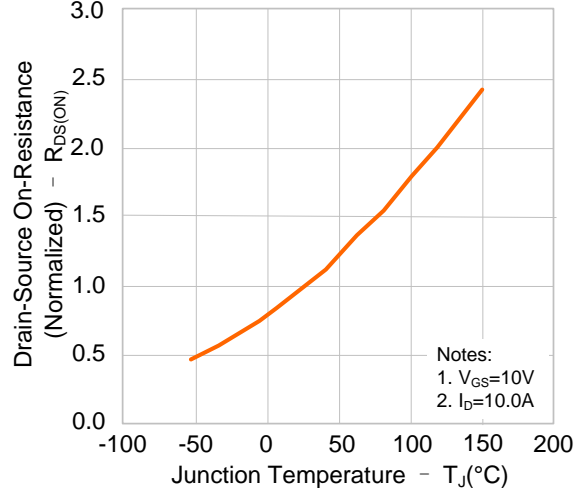


Figure 9. Max. Safe Operating Area

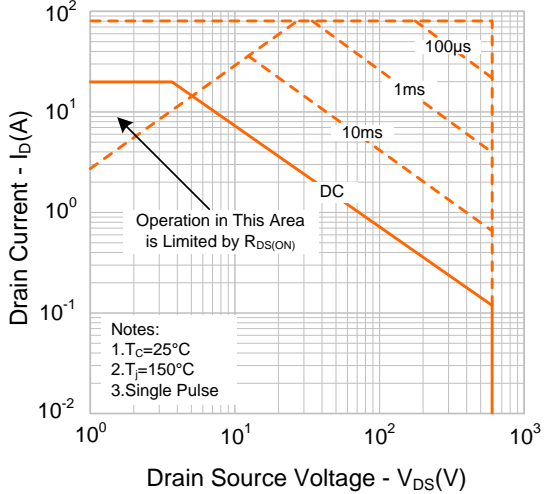
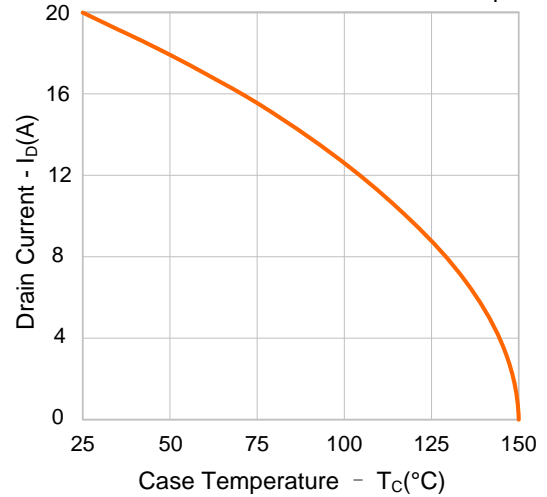
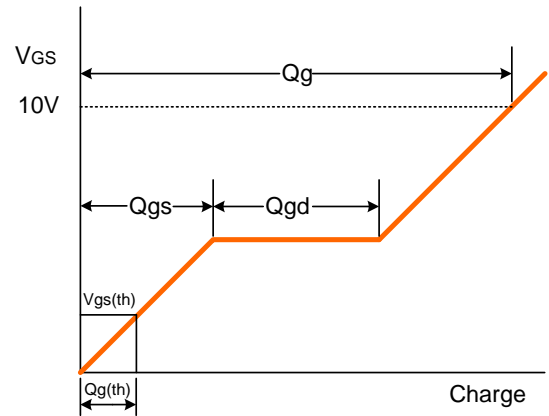
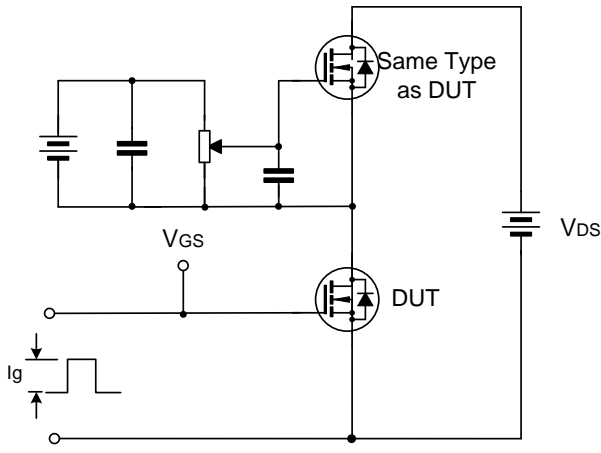


Figure 10. Maximum Drain Current vs. Case Temperature

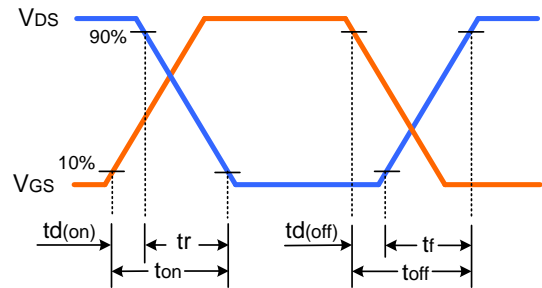
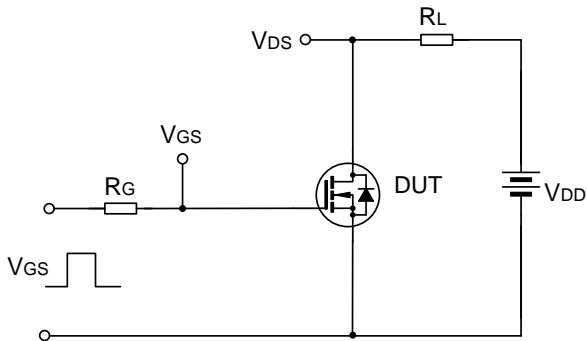


TYPICAL TEST CIRCUIT

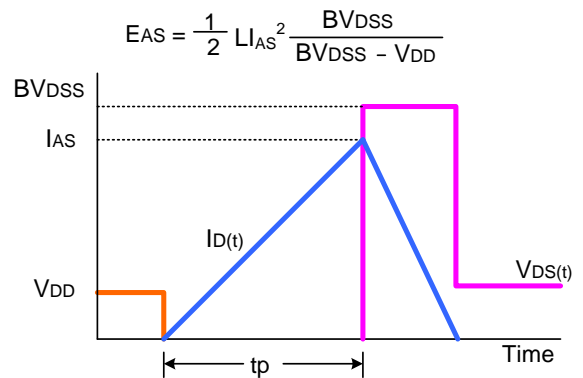
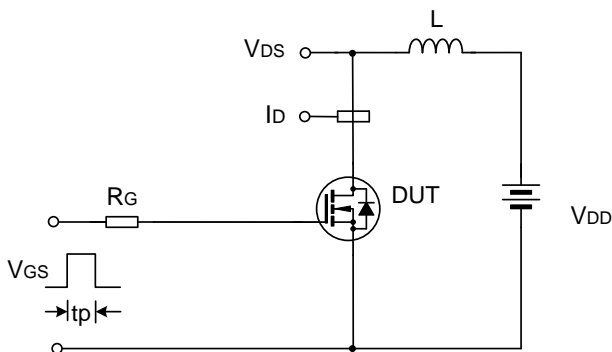
Gate Charge Test Circuit & Waveform



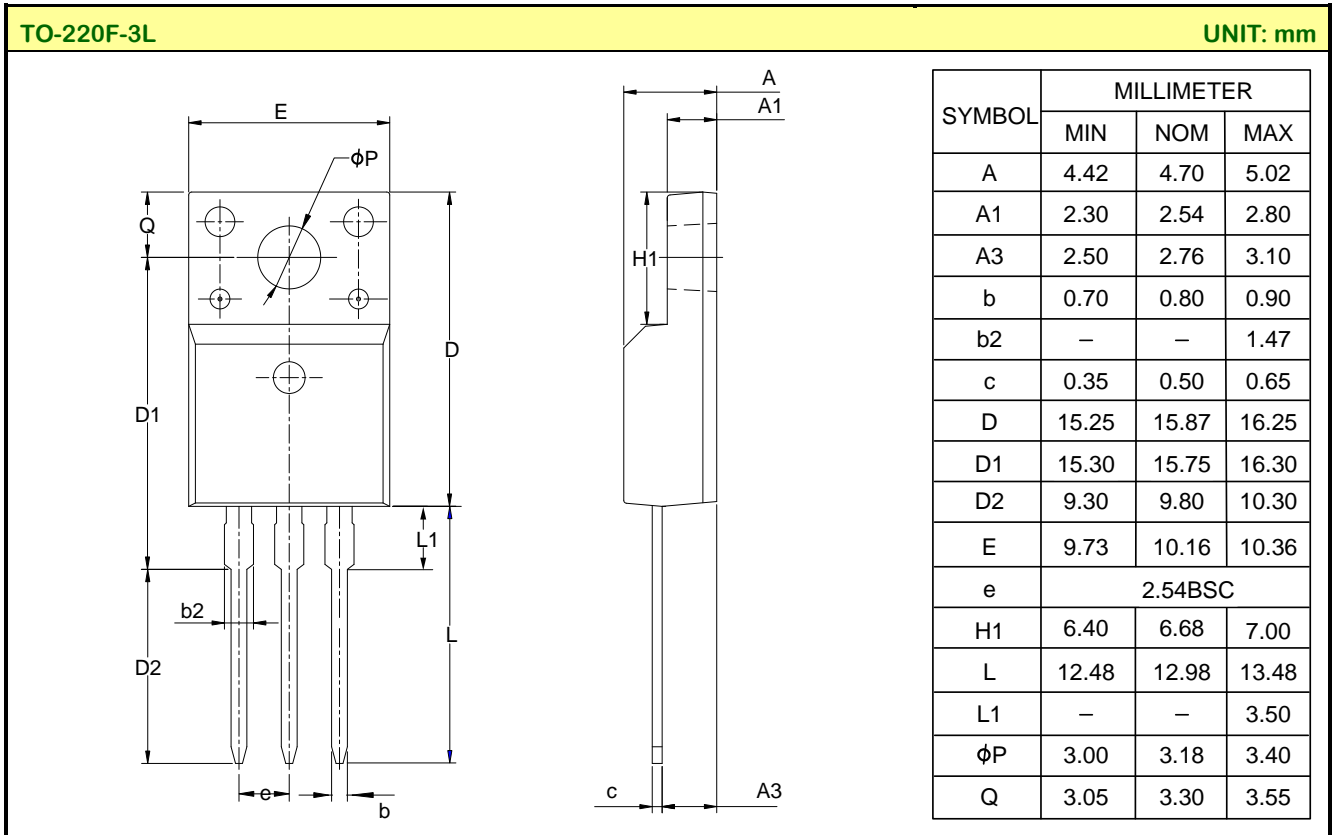
Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



PACKAGE OUTLINE



Important notice :

1. The instructions are subject to change without notice!
2. Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current. Please read the instructions carefully before using our products, including the circuit operation precautions.
3. Our products are consumer electronic products or the other civil electronic products.
4. When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
5. It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.
6. Product promotion is endless, our company will wholeheartedly provide customers with better products!
7. Website: <http://www.silan.com.cn>

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Rev.: 1.9

Revision History:

1. Delete package of TO-3P
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Rev.: 1.8

Revision History:

1. Update electrical drawings and typical circuit diagrams
-

Rev.: 1.7

Revision History:

1. Deleted NOMENCLATURE
 2. Modify Important notice.
-

Rev.: 1.6

Revision History:

1. Modify the EAS test condition.
-

Rev.: 1.5

Revision History:

1. Modify the package information of TO-220F-3L
-

Rev.: 1.4

Revision History:

1. Modify the thermal characteristics
-

Rev.: 1.3

Revision History:

1. Modify the ordering information
-

Rev.: 1.2

Revision History:

1. Change the schematic diagram of MOS
-

Rev.: 1.1

Revision History:

1. Add the package of TO-3PN
-

Rev.: 1.0

Revision History:

1. Initial release
-
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